

P/1071-1524

METHOD OF MANUFACTURING NONRECIPROCAL
CIRCUIT DEVICE, NONRECIPROCAL CIRCUIT DEVICE,
AND COMMUNICATION APPARATUS

ABSTRACT OF THE DISCLOSURE

5 A compact and highly reliable nonreciprocal circuit
device can be manufactured at low cost. Marking is
clearly performed on a surface of the nonreciprocal
circuit device. In a method of manufacturing the
nonreciprocal circuit device, after components
10 constituting the device are joined together, solder is
applied at portions where the components are bonded with
each other. The magnetic force of a permanent magnet is
adjusted and then laser marking is performed on a surface
of a metal case. Next, the nonreciprocal circuit device
15 is heated to perform together solder bonding, thermal
aging of the permanent magnet, and the removal of stains
left due to marking. Then, after checking the
characteristics of the device, delivery inspection is
conducted to complete the manufacturing process.

204270" 85295001